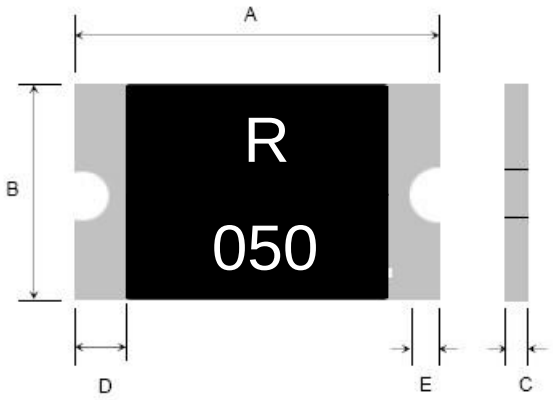
TERMINAL PAD SOLDERABILITY：

Meets EIA Specification RS186-9E
And ANSI/J-STD-002 Category 3.



TERMINAL PAD MATERIALS：

Tin-Plated Nickel-Copper
Lead-Free，ROHS Compliant

TABLE I. DIMENSIONS： Unit：mm

Model	A		B		C		D	E
	Min	Max	Min	Max	Min	Max	Min	Min
SMD2920-050	6.73	7.98	4.80	5.44	0.60	1.20	0.30	0.25

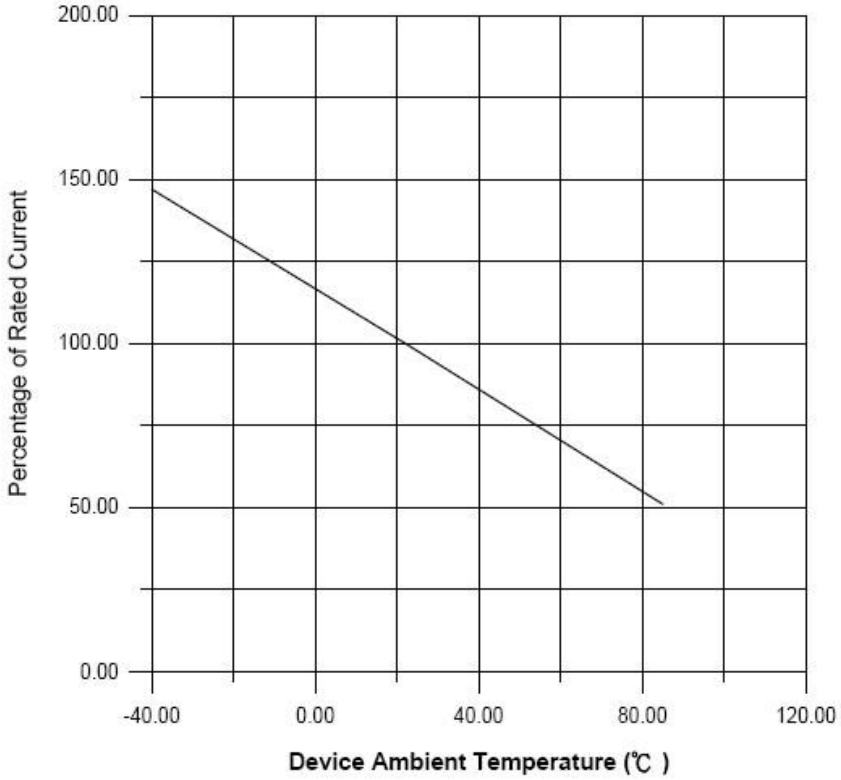
TABLE II. PERFORMANCE RATINGS：

Model	Vmax	Imax	Ihold@25℃	Itrip@25℃	Pd Typ.	Maximum Time TO Trip		Resistance	
	(Vdc)	(A)	(A)	(A)	(W)	Current (A)	Time (Sec)	Rimin (Ω)	Rimax (Ω)
SMD2920-050	60	10	0.50	1.00	1.5	2.5	4.0	0.180	1.400

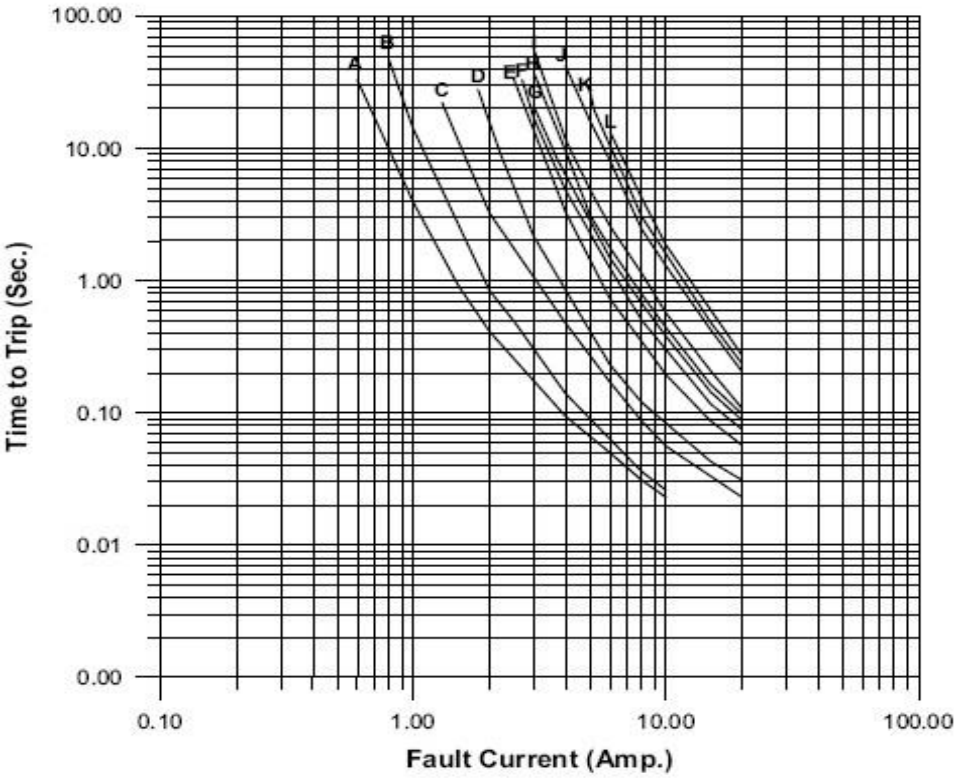
THERMAL DERATING CHART FOR SMD2920 SERIES-IHOLD(Amps) RECOMMENDED DATA

Model	Ambient Operation Temperature								
	-40℃	-20℃	0℃	25℃	40℃	50℃	60℃	70℃	85℃
SMD2920-050	0.76	0.67	0.59	0.50	0.42	0.38	0.33	0.29	0.23

THERMAL DERATING CURVE FOR SMD2920 SERIES

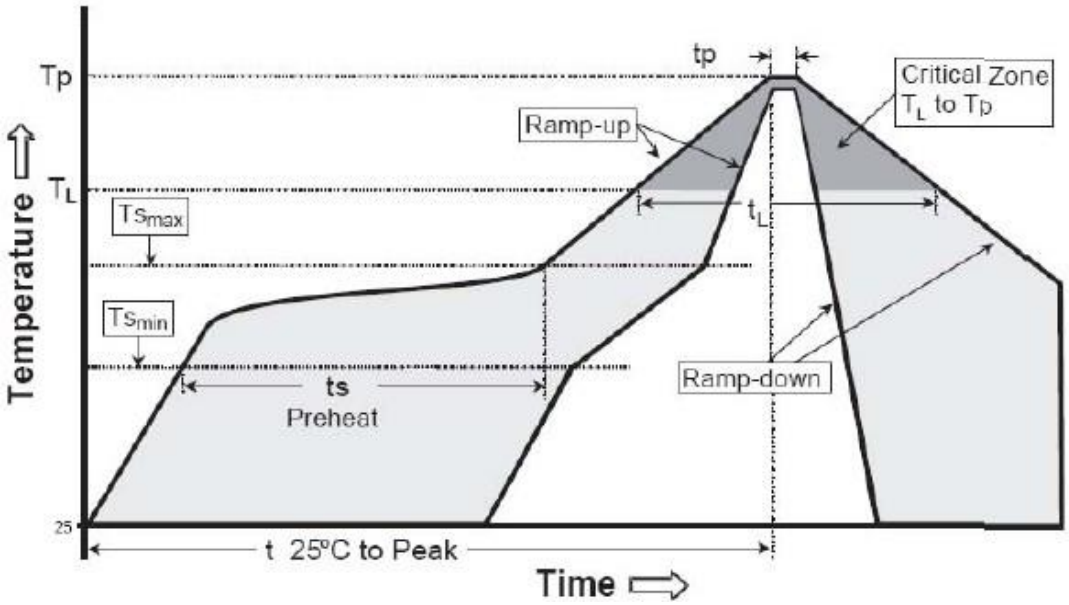


AVERAGE TIME-CURRENT CURVE FOR SMD2920 SERIES



A-SMD2920-030
B-SMD2920-050
C-SMD2920-075
D-SMD2920-100
E-SMD2920-125
F-SMD2920-150
G-SMD2920-185
H-SMD2920-200 24V
I-SMD2920-200
J-SMD2920-250
K-SMD2920-260
L-SMD2920-300

SOLDER REFLOW



RECOMMENDED CONCITIONS

Profile Feature	Pd-Free Assembly
Average Ramp-Up Rate(Tsmax to Tp)	3℃/second max
Preheat —Temperature Min(Tsmin) —Temperature Max(Tsmax) —Time(Tsmin to Tsmax)	 150℃ 200℃ 60-180seconds
Time maintained above： —Temperature(TL) —Time(tL)	 217℃ 60-150seconds
Peak Temperature(Tp)	260℃
Time within 5℃ of actual Peak Temperature(tp)	20-40seconds
Ramp-Down Rate	6℃/second max.
Time 25℃ to Peak Temperature	8minutes max.
Storage Condition	0℃~35℃，≤70%RH

Note：1.All temperature refer to topside of the package，measured on the package body surface.
2.If reflow temperature exceed the recommended profile，devices

PACKAGING

Part Number	Component Package	Quantity
SMD2920-050	2920	1500